

**Amendments to the Claims**

Claims 1-84 (Cancelled)

85. (Currently amended) A sputtering target comprising Zr and one or more elements selected from the group consisting of Ba, Be, Ca, Ce, Co, Cs, Dy, Er, Fe, Gd, Ho, La, ~~Mg~~, Mn, Mo, Nd, Pr, Sc, Sm, Sr, V, W, and Yb; the Zr being the majority element of the target.

86. (Original) The sputtering target of claim 85 wherein the Zr concentration within the target is at least 70%.

87. (Original) The sputtering target of claim 85 wherein the Zr concentration within the target is at least 90%.

88. (Original) The sputtering target of claim 85 wherein the Zr concentration within the target is at least 94%.

89. (Original) The sputtering target of claim 85 wherein the Zr concentration within the target is at least 97%.

90. (Original) The sputtering target of claim 85 wherein the Zr concentration within the target is less than 98%.

91. (Previously presented) The sputtering target of claim 85 wherein the total non-zirconium metal content of the target is in a range of from 0.001% to 50% of the target.

92. (Previously presented) The sputtering target of claim 85 wherein the total non-zirconium metal content of the target is in a range of 0.001% to 10% of the target.

93. (Previously presented) The sputtering target of claim 85 wherein the total non-zirconium metal content of the target is at least 0.01% of the target.

94. (Previously presented) The sputtering target of claim 85 wherein the total non-zirconium metal content of the target is at least 0.1% of the target.

95. (Previously presented) The sputtering target of claim 85 wherein the total non-zirconium metal content of the target is at least 1% of the target.

96. (Previously presented) The sputtering target of claim 85 wherein the total non-zirconium metal content of the target is at least 2% of the target.

97. (Currently amended) The sputtering target of claim 85 further comprising one or more elements selected from the group consisting of Mg, Al, B, Hf, Nb, Ni, Ta, Y and Ti.

98. (Previously presented) A sputtering target consisting essentially of a material having a purity of at least 99.95%, by weight, the material comprising Zr and Ti; the Zr being the majority element of the target and being present to a concentration within the target of at least 55%.

99. (Original) The sputtering target of claim 98 wherein the Zr concentration within the target is at least 70%.

100. (Original) The sputtering target of claim 98 wherein the Zr concentration within the target is at least 90%.

101. (Original) The sputtering target of claim 98 wherein the Zr concentration within the target is at least 94%.

102. (Original) The sputtering target of claim 98 wherein the Zr concentration within the target is at least 97%.

103. (Original) The sputtering target of claim 98 wherein the Zr concentration within the target is less than 98%.

104. (Currently amended) A sputtering target comprising Ti and greater than 2% 0.2% B, by weight; the Ti being the majority element of the target.

105. (Original) The sputtering target of claim 104 wherein the Ti concentration within the target is at least 70%.

106. (Original) The sputtering target of claim 104 wherein the Ti concentration within the target is at least 90%.

107. (Original) The sputtering target of claim 104 wherein the Ti concentration within the target is at least 94%.

108. (Original) The sputtering target of claim 104 wherein the Ti concentration within the target is at least 97%.

Claims 109-117 (Cancelled).

118. (Original) The sputtering target of claim 104 consisting of Ti and B.